



Attorney's Docket No. 07977/226002/US3548D1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hisashi Ohtani                  Art Unit : 1765  
Serial No.: 09/596,755                  Examiner : Robert Kunemund  
Filed        : June 15, 2000  
Title        : MANUFACTURING METHOD OF SEMICONDUCTOR AND  
                  MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

**BOX AF**

Commissioner for Patents  
Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Official Action dated April 3, 2001,  
Paper No. 6, in the above-referenced application, please amend  
the above-identified application as follows:

In the Claims:

Please amend claims 2, 8, 14, 20, 22, 29, 36, and 41 as  
follows:

2. (Amended) A method for manufacturing a semiconductor  
device comprising steps of:

forming a semiconductor film over a substrate; and

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*Susan Regan*  
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